

BAP51L

Silicon PIN diode

Rev. 01 — 11 March 2005

Product data sheet

1. Product profile

1.1 General description

Planar PIN diode in a SOD882 leadless ultra small SMD plastic package.

1.2 Features


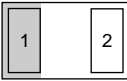
- High speed switching for RF signals
- Low diode capacitance
- Low forward resistance
- Very low series inductance
- For applications up to 3 GHz

1.3 Applications

- RF attenuators and switches

2. Pinning information

Table 1: Pinning

Pin	Description	Simplified outline	Symbol
1	cathode	[1]	 <i>sym006</i>
2	anode	 Transparent top view	

[1] The marking bar indicates the cathode

3. Ordering information

Table 2: Ordering information

Type number	Package		
	Name	Description	Version
BAP51L	-	leadless ultra small plastic package; 2 terminals; body 1.0 × 0.6 × 0.5 mm	SOD882

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4. Marking

Table 3: Marking

Type number	Marking code
BAP51L	E2

5. Limiting values

Table 4: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	60	V
I_F	forward current		-	100	mA
P_{tot}	total power dissipation	$T_{sp} = 90\text{ °C}$	-	500	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

6. Thermal characteristics

Table 5: Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		100	K/W

7. Characteristics

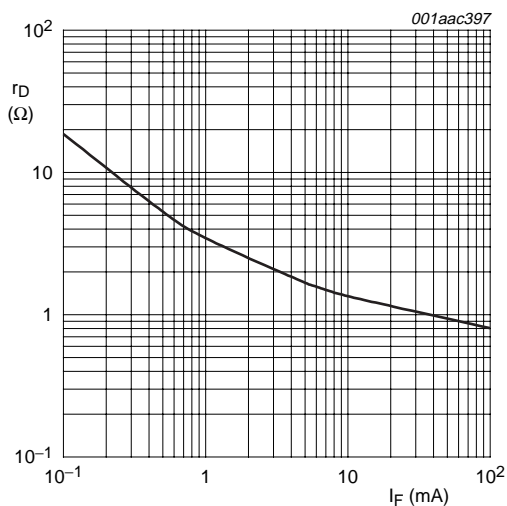
Table 6: Electrical characteristics

$T_j = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 50\text{ mA}$	-	0.95	1.1	V
I_R	reverse current	$V_R = 50\text{ V}$	-	-	100	nA
C_d	diode capacitance	$f = 1\text{ MHz}$; see Figure 2				
		$V_R = 0\text{ V}$	-	0.30	-	pF
		$V_R = 1\text{ V}$	-	0.23	0.4	pF
		$V_R = 5\text{ V}$	-	0.17	0.3	pF
r_D	diode forward resistance	$f = 100\text{ MHz}$; see Figure 1				
		$I_F = 0.5\text{ mA}$	-	5.3	9	Ω
		$I_F = 1\text{ mA}$	-	3.5	6.5	Ω
		$I_F = 10\text{ mA}$	-	1.4	2.5	Ω
		$I_F = 100\text{ mA}$	-	0.9	1.5	Ω
$ s_{21} ^2$	isolation	$V_R = 0\text{ V}$; see Figure 4				
		$f = 900\text{ MHz}$	-	19	-	dB
		$f = 1800\text{ MHz}$	-	15	-	dB
		$f = 2450\text{ MHz}$	-	13	-	dB

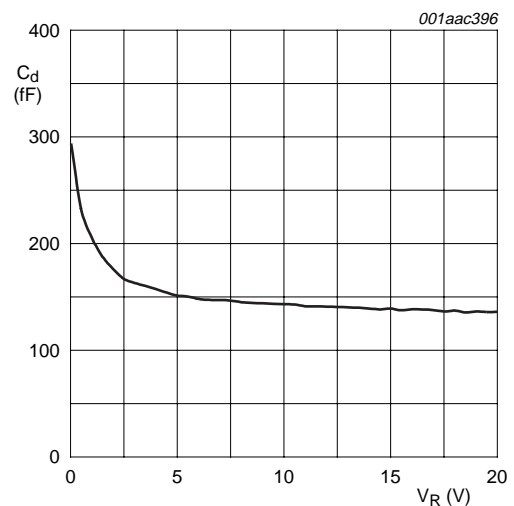
Table 6: Electrical characteristics ...continued
T_j = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
s ₂₁ ²	insertion loss	I _F = 0.5 mA; see Figure 3				
		f = 900 MHz	-	0.4	-	dB
		f = 1800 MHz	-	0.39	-	dB
s ₂₁ ²	insertion loss	I _F = 1 mA; see Figure 3				
		f = 900 MHz	-	0.26	-	dB
		f = 1800 MHz	-	0.26	-	dB
s ₂₁ ²	insertion loss	I _F = 10 mA; see Figure 3				
		f = 900 MHz	-	0.11	-	dB
		f = 1800 MHz	-	0.11	-	dB
s ₂₁ ²	insertion loss	I _F = 100 mA; see Figure 3				
		f = 900 MHz	-	0.07	-	dB
		f = 1800 MHz	-	0.07	-	dB
τ _L	charge carrier life time	I _F = 100 mA; see Figure 3				
		f = 900 MHz	-	0.07	-	dB
		f = 1800 MHz	-	0.07	-	dB
L _S	series inductance	I _F = 100 mA; f = 100 MHz				
		f = 900 MHz	-	0.09	-	dB
		f = 2450 MHz	-	0.09	-	dB
τ _L	charge carrier life time	when switched from I _F = 10 mA to I _R = 6 mA; R _L = 100 Ω; measured at I _R = 3 mA	-	0.55	-	μs
L _S	series inductance	I _F = 100 mA; f = 100 MHz	-	0.6	-	nH



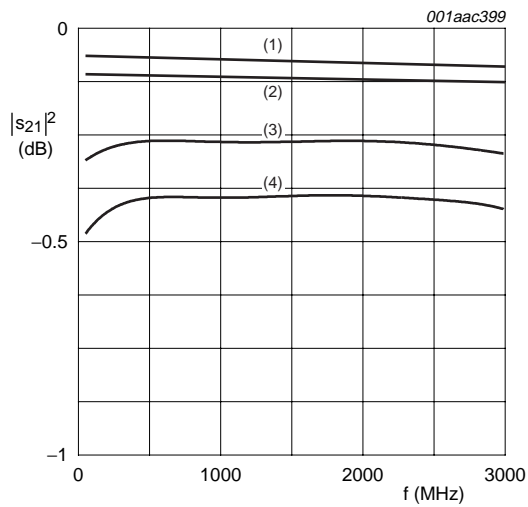
f = 100 MHz; T_j = 25 °C

Fig 1. Forward resistance as a function of forward current; typical values



f = 1 MHz; T_j = 25 °C

Fig 2. Diode capacitance as a function of reverse voltage; typical values

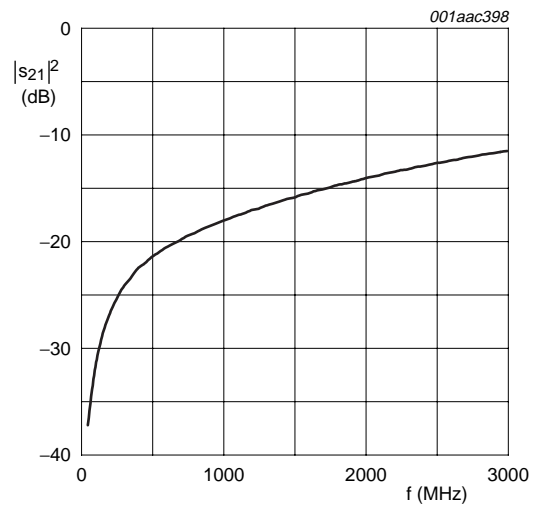


$T_{amb} = 25\text{ }^{\circ}\text{C}$

- (1) $I_F = 100\text{ mA}$
- (2) $I_F = 10\text{ mA}$
- (3) $I_F = 1\text{ mA}$
- (4) $I_F = 0.5\text{ mA}$

Diode inserted in series with a $50\text{ }\Omega$ stripline circuit and biased via the analyzer Tee network

Fig 3. Insertion loss ($|s_{21}|^2$) of the diode as a function of frequency; typical values



$T_{amb} = 25\text{ }^{\circ}\text{C}$

Diode zero biased and inserted in series with a $50\text{ }\Omega$ stripline circuit

Fig 4. Isolation ($|s_{21}|^2$) of the diode as a function of frequency; typical values

8. Package outline

Leadless ultra small plastic package; 2 terminals; body 1.0 x 0.6 x 0.5 mm

SOD882

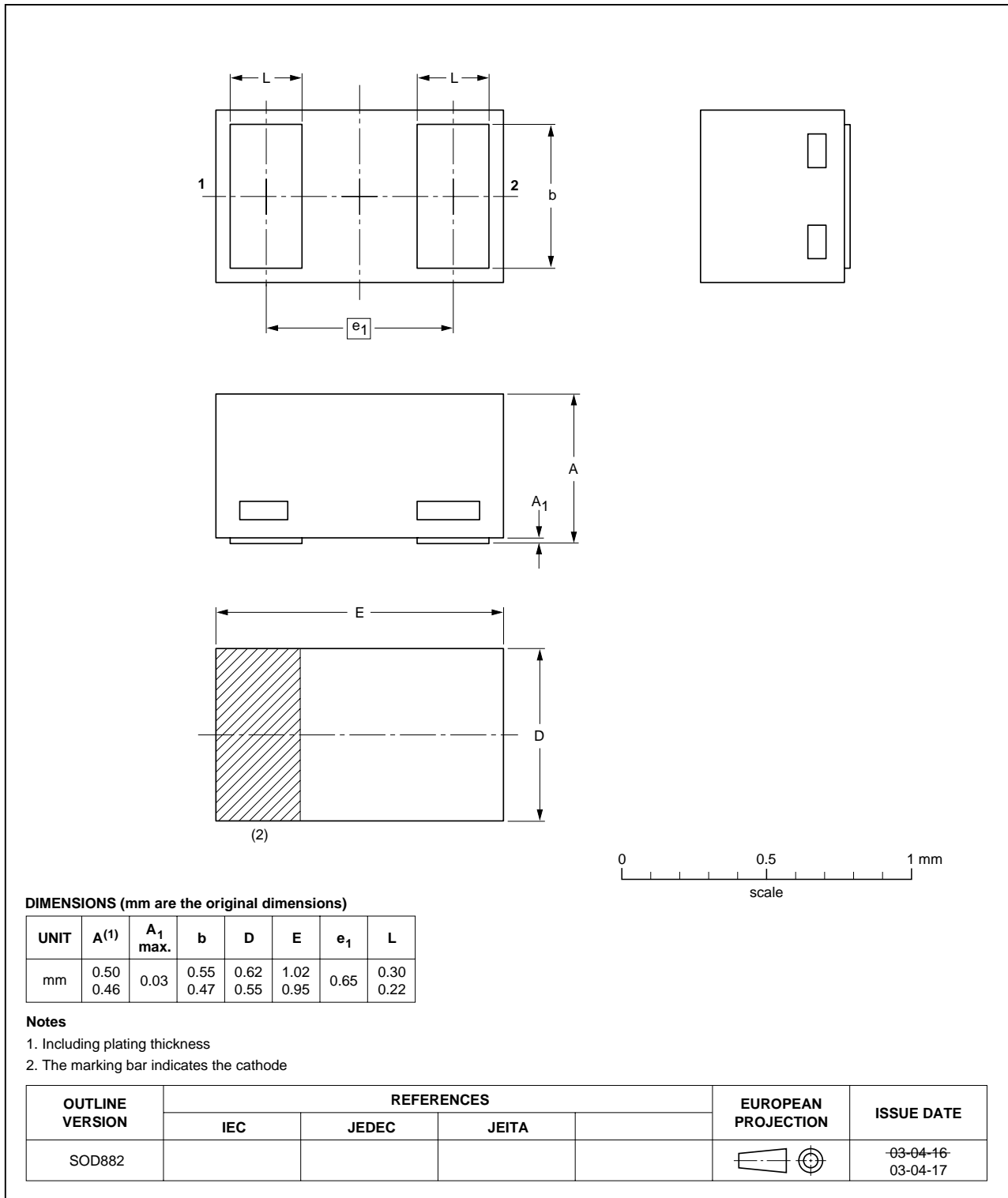


Fig 5. Package outline SOD882

9. Revision history

Table 7: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
BAP51L_1	20050311	Product data sheet	-	9397 750 14554	-

10. Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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